

April 1988 Revised July 1999

### 74F174

# **Hex D-Type Flip-Flop with Master Reset**

#### **General Description**

The 74F174 is a high-speed hex D-type flip-flop. The device is used primarily as a 6-bit edge-triggered storage register. The information on the D inputs is transferred to storage during the LOW-to-HIGH clock transition. The device has a Master Reset to simultaneously clear all flip-flops.

#### **Features**

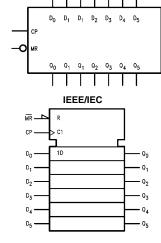
- Edge-triggered D-type inputs
- Buffered positive edge-triggered clock
- Asynchronous common reset
- Guaranteed 4000V minimum ESD protection

#### **Ordering Code:**

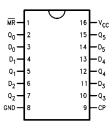
Order Number	Package Number	Package Description
74F174SC	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
74F174SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F174PC	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Logic Symbols**



#### **Connection Diagram**



## **Unit Loading/Fan Out**

Pin Names	Decerinties	U.L.	Input I <sub>IH</sub> /I <sub>IL</sub>	
Pin Names	Description	HIGH/LOW	Output I <sub>OH</sub> /I <sub>OL</sub>	
D <sub>0</sub> –D <sub>5</sub>	Data Inputs	1.0/1.0	20 μA/-0.6 mA	
CP	Clock Pulse Input (Active Rising Edge)	1.0/1.0	20 μA/-0.6 mA	
MR	Master Reset Input (Active LOW)	1.0/1.0	20 μA/-0.6 mA	
Q <sub>0</sub> –Q <sub>5</sub>	Outputs	50/33.3	-1 mA/20 mA	

#### **Functional Description**

The 74F174 consists of six edge-triggered D-type flip-flops with individual D inputs and Q outputs. The Clock (CP) and Master Reset (MR) are common to all flip-flops. Each D input's state is transferred to the corresponding flip-flop's output following the LOW-to-HIGH Clock (CP) transition. A LOW input to the Master Reset (MR) will force all outputs LOW independent of Clock or Data inputs. The 74F174 is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

#### **Truth Table**

	Inputs		Outputs
MR	СР	D <sub>n</sub>	Q <sub>n</sub>
L	Х	Х	L
Н	~	Н	Н
Н	~	L	L

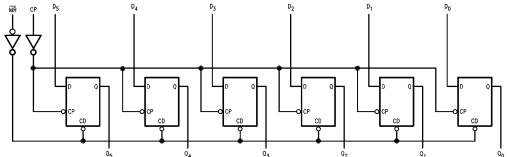
H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

= LOW-to-HIGH Clock Transition

## **Logic Diagram**



 $\dot{Q_5}$   $\dot{Q_4}$   $\dot{Q_3}$   $\dot{Q_2}$   $\dot{Q_1}$ Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

#### **Absolute Maximum Ratings**(Note 1)

Recommended Operating Conditions

 $\begin{array}{ll} \mbox{Storage Temperature} & -65^{\circ}\mbox{C to } +150^{\circ}\mbox{C} \\ \mbox{Ambient Temperature under Bias} & -55^{\circ}\mbox{C to } +125^{\circ}\mbox{C} \\ \end{array}$ 

Ambient Temperature under Bias -55°C to +125°C

Junction Temperature under Bias -55°C to +150°C

V<sub>CC</sub> Pin Potential to Ground Pin

Input Voltage (Note 2)

Input Current (Note 2)

-30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with  $V_{CC} = 0V$ )

 $\begin{array}{ll} \mbox{Standard Output} & -0.5\mbox{V to V}_{\mbox{CC}} \\ \mbox{3-STATE Output} & -0.5\mbox{V to +5.5}\mbox{V} \end{array}$ 

Current Applied to Output

 $\label{eq:lower_lower} \mbox{in LOW State (Max)} \qquad \mbox{twice the rated $I_{OL}$ (mA)} \\ \mbox{ESD Last Passing Voltage (Min)} \qquad \mbox{4000V}$ 

Free Air Ambient Temperature  $0^{\circ}\text{C} \text{ to } +70^{\circ}\text{C}$  Supply Voltage +4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

#### **DC Electrical Characteristics**

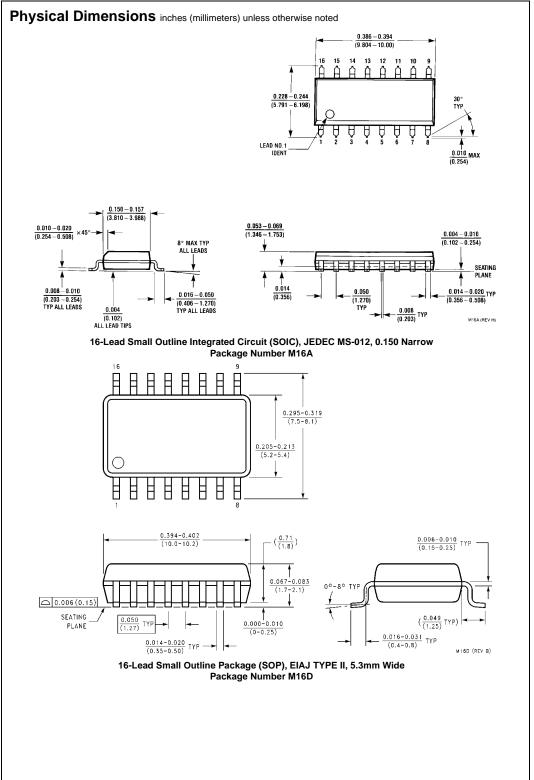
Symbol	l Parameter		Min	Тур	Max	Units	v <sub>cc</sub>	Conditions	
V <sub>IH</sub>	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Voltage				-1.2	V	Min	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	Output HIGH	10% V <sub>CC</sub>	2.5			V	Min	I <sub>OH</sub> = -1 mA	
	Voltage	5% V <sub>CC</sub>	2.7			V	IVIIII	$I_{OH} = -1 \text{ mA}$	
V <sub>OL</sub>	Output LOW	10% V <sub>CC</sub>			0.5	V	Min	I <sub>OL</sub> = 20 mA	
	Voltage	10% V <sub>CC</sub>			0.5	V	IVIII	I <sub>OL</sub> = 20 mA	
I <sub>IH</sub>	Input HIGH				5.0		Max	\/ - 2.7\/	
	Current				5.0	μА	IVIAX	$V_{IN} = 2.7V$	
I <sub>BVI</sub>	Input HIGH Current				7.0	μА	Max	V <sub>IN</sub> = 7.0V	
	Breakdown Test				7.0	μА	IVIAX	$v_{IN} = 7.0v$	
I <sub>CEX</sub>	Output HIGH				50		Max	V -V	
	Leakage Current				50	μА	IVIAX	$V_{OUT} = V_{CC}$	
V <sub>ID</sub>	Input Leakage		4.75			V	0.0	$I_{ID} = 1.9 \mu A$	
	Test		4.75			V	0.0	All Other Pins Grounded	
l <sub>OD</sub>	Output Leakage				3.75	μА	0.0	V <sub>IOD</sub> = 150 mV	
	Circuit Current				3.73	μΛ	0.0	All Other Pins Grounded	
I <sub>IL</sub>	Input LOW Current				-0.6	mA	Max	$V_{IN} = 0.5V$	
los	Output Short-Circuit Current		-60		-150	mA	Max	V <sub>OUT</sub> = 0V	
Іссн	Power Supply Current			30	45	mA	Max	CP = _	
								$D_n = \overline{MR} = HIGH$	
I <sub>CCL</sub>	Power Supply Current			30	45	mA	Max	$V_O = LOW$	

# **AC Electrical Characteristics**

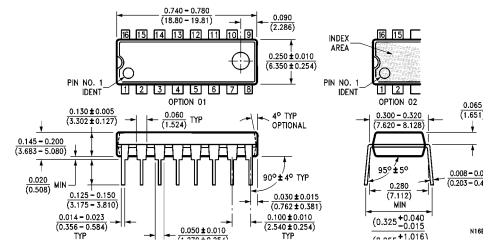
Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_L = 50 \text{ pF}$			v <sub>cc</sub> =	to +125°C : +5.0V 50 pF	$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$ $C_L = 50$ pF		Units
		Min	Тур	Max	Min	Max	Min	Max	
f <sub>MAX</sub>	Maximum Clock Frequency	80			70		80		MHz
t <sub>PLH</sub>	Propagation Delay	3.5	5.5	8.0	3.0	10.0	3.5	9.0	20
t <sub>PHL</sub>	CP to Q <sub>n</sub>	4.0	7.0	10.0	4.0	12.0	4.0	11.0	ns
t <sub>PHL</sub>	Propagation Delay  MR to Q <sub>n</sub>	5.0	10.0	14.0	5.0	16.0	5.0	15.0	ns

## **AC Operating Requirements**

Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$		$T_A = -55^{\circ}C \text{ to } +125^{\circ}$ $V_{CC} = +5.0V$		$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$		Units
		Min	Max	Min	Max	Min	Max	
t <sub>S</sub> (H)	Setup Time, HIGH or LOW	4.8		5.0		4.8		ns
t <sub>S</sub> (L)	D <sub>n</sub> to CP	4.0		5.0		4.0		
t <sub>H</sub> (H)	Hold Time, HIGH or LOW	0		2.0		0		
t <sub>H</sub> (L)	D <sub>n</sub> to CP	0		2.0		0		
t <sub>W</sub> (H)	CP Pulse Width	4.0		5.0		4.0		
$t_W(L)$	HIGH or LOW	6.0		7.5		6.0		ns
t <sub>W</sub> (L)	MR Pulse Width, LOW	5.0		6.5		5.0		ns
t <sub>REC</sub>	Recovery Time, MR to CP	5.0		6.0		5.0		



#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N16E

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